

# HIL40N120VF

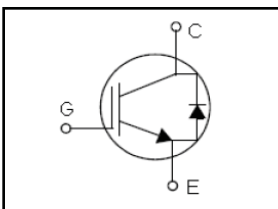
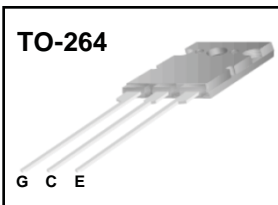
## 1200V Field Stop Trench IGBT

Employing Field Stop technology, CO-PAK, IGBT with FRD. 1200V/40A planar gate IGBTs provide low Conduction, switching losses and very good ruggedness.

### Applications

Induction Heating, UPS, welding converters and general purpose inverters.

$V_{CES} = 1200\text{ V}$
$I_C = 40\text{ A}$
$V_{CE(sat) typ} = 2.0\text{ V}$



### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$I_C$	Collector Current – Continuous ( $T_C = 25^\circ\text{C}$ )	64	A
	Collector Current – Continuous ( $T_C = 100^\circ\text{C}$ )	40	A
$I_{CM}$	Collector Current – Pulsed (Note 1)	160	A
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$t_{SC}$	Short circuit withstand time ( $V_{GE}=15\text{V}$ , $V_{CC}=600\text{V}$ , $T_C=125^\circ\text{C}$ )	10	$\mu\text{A}$
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	500	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

**Notes.**

1. Pulse width limited by max junction temperature

### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(IGBT)$	Junction-to-Case	--	0.25	$^\circ\text{C/W}$
$R_{\theta JC}(\text{Diode})$	Junction-to-Case	--	0.7	
$R_{\theta JA}$	Junction-to-Ambient	--	25	

## Package Marking and Odering Information

Device Marking	Week Marking	Package	Packing	Quantity	RoHS Status
HIL40N120VF	YWWX	TO-264	Tube	25	Pb Free
HIL40N120VF	YWWXg	TO-264	Tube	25	Halogen Free

## Electrical Characteristics of the IGBT $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### On Characteristics

$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$V_{CE} = V_{GE}, I_C = 1.5\text{ mA}$	4.0	--	6.0	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{ V},$ $I_C = 40\text{ A}$	$T_C = 25^\circ\text{C}$	--	2.0	2.6	V
			$T_C = 125^\circ\text{C}$	--	2.5	3.2	

### Off Characteristics

$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0\text{ V}, I_C = 250\ \mu\text{A}$	1200	--	--	V
$I_{CES}$	Zero Gate Voltage Collector Current	$V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V}$	--	--	1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{ V}, V_{CE} = 0\text{ V}$	--	--	$\pm 250$	nA

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	6680	8680	pF
$C_{oss}$	Output Capacitance		--	295	380	pF
$C_{rss}$	Reverse Transfer Capacitance		--	76	100	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Time	$V_{CC} = 600\text{ V}, I_C = 40\text{ A},$ $R_G = 10\ \Omega, V_{GE} = 15\text{ V}$ Inductive load, $T_C = 25^\circ\text{C}$	--	50	--	ns
$t_r$	Turn-On Rise Time		--	65	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	295	--	ns
$t_f$	Turn-Off Fall Time		--	85	--	ns
$E_{on}$	Turn-On Switching Loss		--	2.3	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	2.2	--	mJ
$E_{ts}$	Total Switching Loss		--	4.5	--	mJ
$t_{d(on)}$	Turn-On Time	$V_{CC} = 600\text{ V}, I_C = 40\text{ A},$ $R_G = 10\ \Omega, V_{GE} = 15\text{ V}$ Inductive load, $T_C = 125^\circ\text{C}$	--	90	--	ns
$t_r$	Turn-On Rise Time		--	70	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	415	--	ns
$t_f$	Turn-Off Fall Time		--	165	--	ns
$E_{on}$	Turn-On Switching Loss		--	2.65	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	3.2	--	mJ
$E_{ts}$	Total Switching Loss		--	5.85	--	mJ
$Q_g$	Total Gate Charge	$V_{CC} = 600\text{ V}, I_C = 40\text{ A},$ $V_{GE} = 15\text{ V}$	--	225	290	nC
$Q_{ge}$	Gate-Emitter Charge		--	55	--	nC
$Q_{gc}$	Gate-Collector Charge		--	90	--	nC
$I_{C(SC)}$	Short Circuit Collector Current	$V_{CC} = 600\text{ V}, t_{SC} \leq 10\text{ s},$ $V_{GE} = 15\text{ V}, T_C = 25^\circ\text{C}$	--	310	--	A

**Electrical Characteristics of the Diode**

$V_{FM}$	Diode Forward Voltage	$I_F = 40\text{ A}, V_R = 600\text{ V}$ $di_F/dt = 200\text{ A}/\mu\text{s}, T_C = 25^\circ\text{C}$	--	2.6	--	V
$t_{rr}$	Diode Reverse Recovery Time		--	400	--	ns
$I_{rr}$	Diode Peak Reverse Recovery Current		--	7.7	--	A
$Q_{rr}$	Diode Reverse Recovery Charge		--	1000	--	$\mu\text{C}$
$V_{FM}$	Diode Forward Voltage	$I_F = 40\text{ A}, V_R = 600\text{ V}$ $di_F/dt = 200\text{ A}/\mu\text{s}, T_C = 125^\circ\text{C}$	--	3.2	--	V
$t_{rr}$	Diode Reverse Recovery Time		--	470	--	ns
$I_{rr}$	Diode Peak Reverse Recovery Current		--	8.0	--	A
$Q_{rr}$	Diode Reverse Recovery Charge		--	1600	--	$\mu\text{C}$

Typical Characteristics

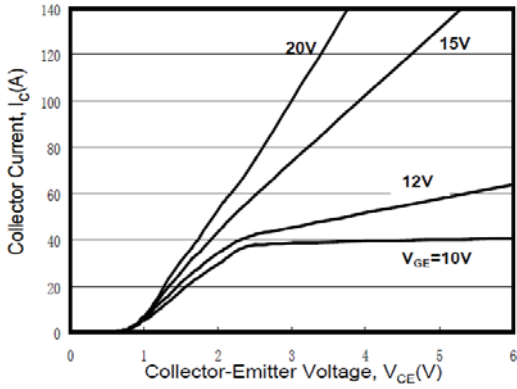


Figure 1. Typical Output Characteristics

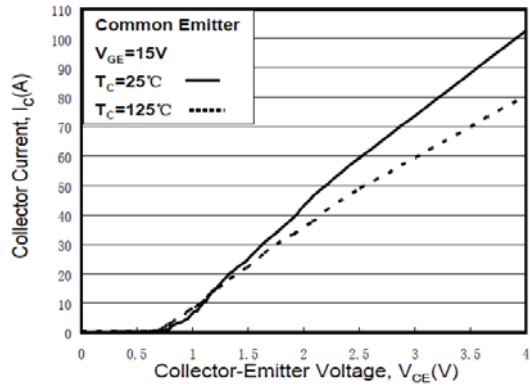


Figure 2. Typical Saturation Voltage Characteristics

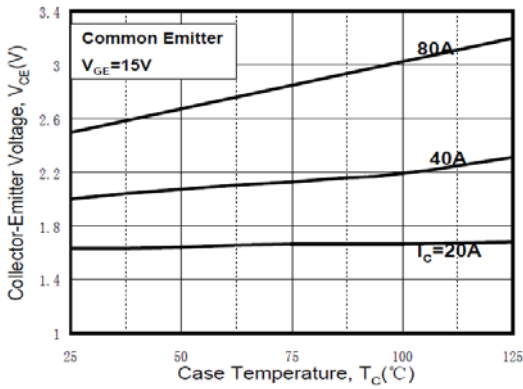


Figure 3. Saturation Voltage vs. Case Temperature at Variant Current Level

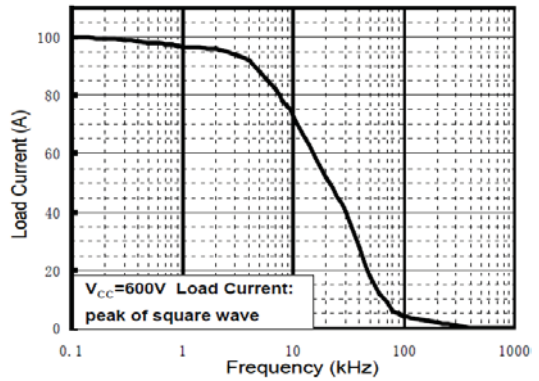


Figure 4. Load Current vs. Frequency

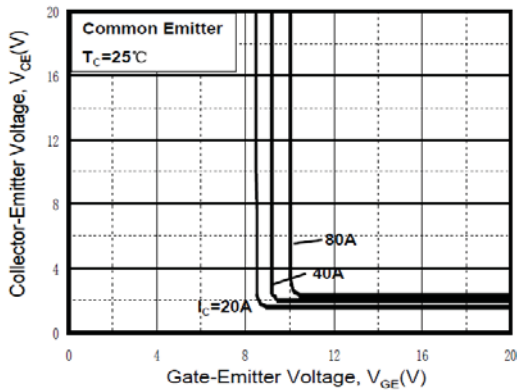


Figure 5. Saturation Voltage vs.  $V_{GE}$

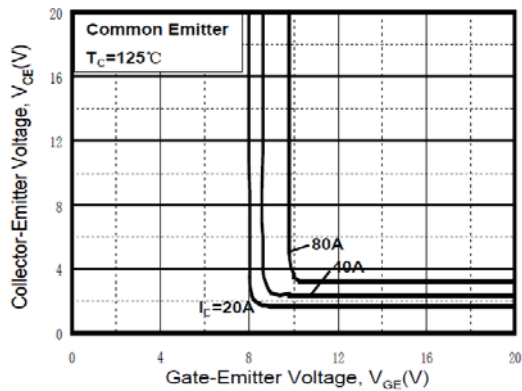


Figure 6. Saturation Voltage vs.  $V_{GE}$

Typical Characteristics

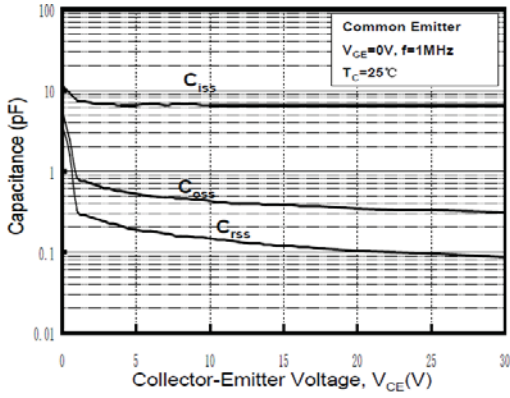


Figure 7. Capacitance Characteristics

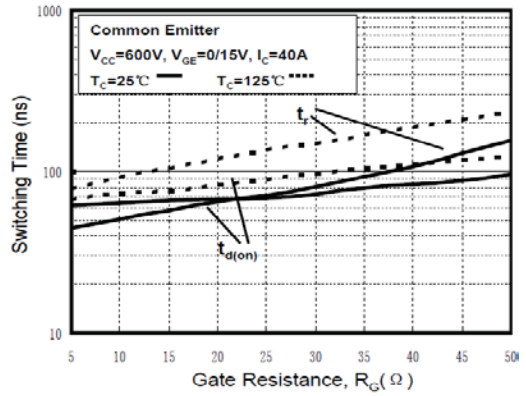


Figure 8. Turn-On Characteristics vs. Gate Resistance

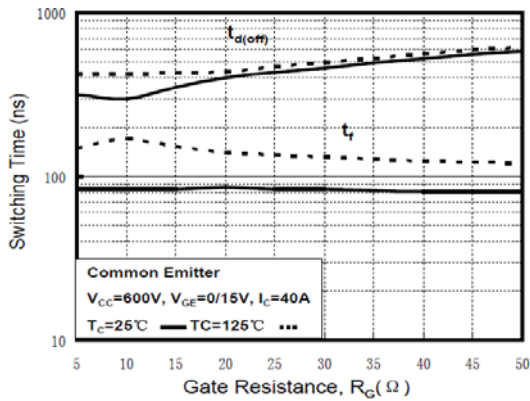


Figure 9. Turn-Off Characteristics vs. Gate Resistance

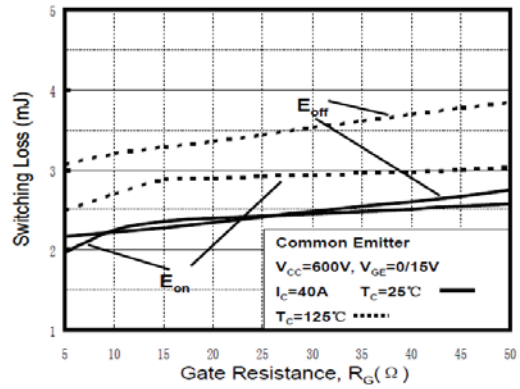


Figure 10. Switching Loss vs. Gate Resistance

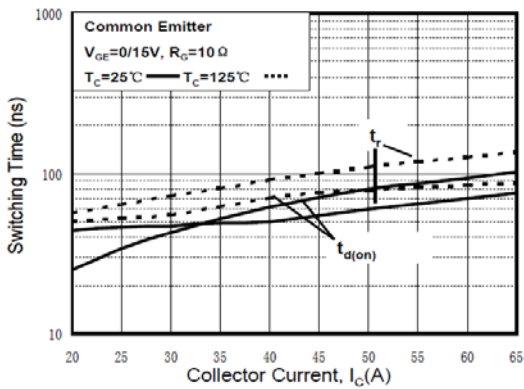


Figure 11. Turn-On Characteristics vs. Collector Current

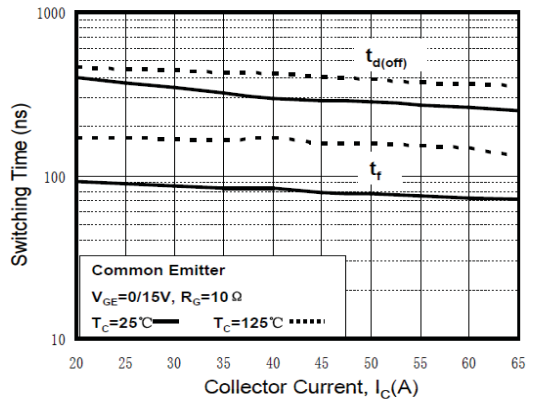


Figure 12. Turn-Off Characteristics vs. Collector Current

Typical Characteristics

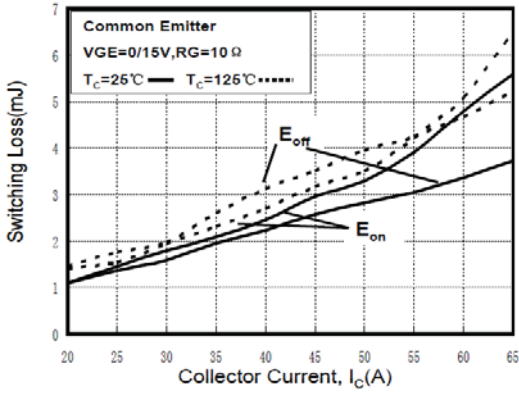


Figure 13. Switching Loss vs. Collector Current

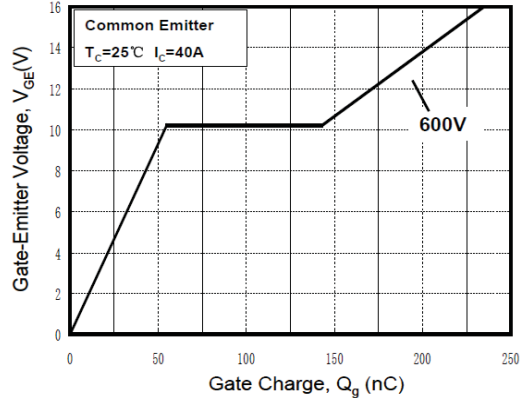


Figure 14. Gate Charge Characteristics

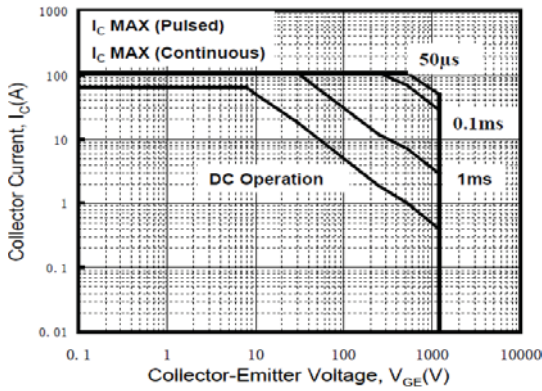


Figure 15. SOA Characteristics

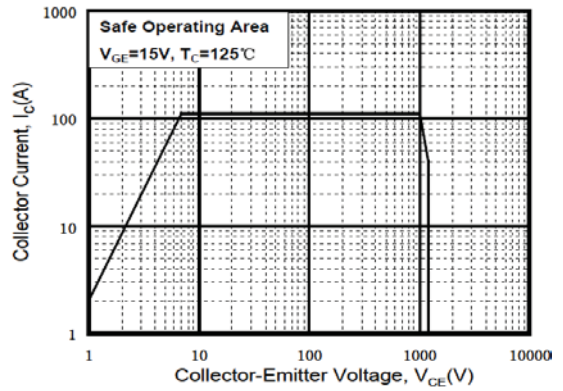


Figure 16. Turn-Off SOA

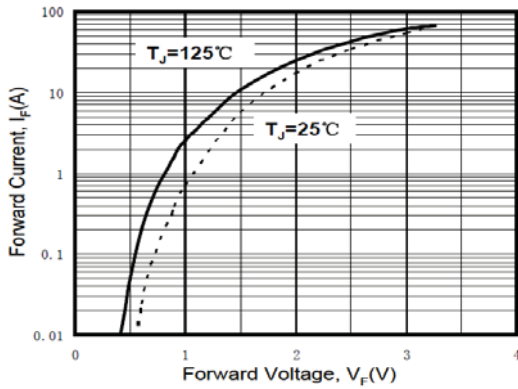


Figure 17. Forward Characteristics

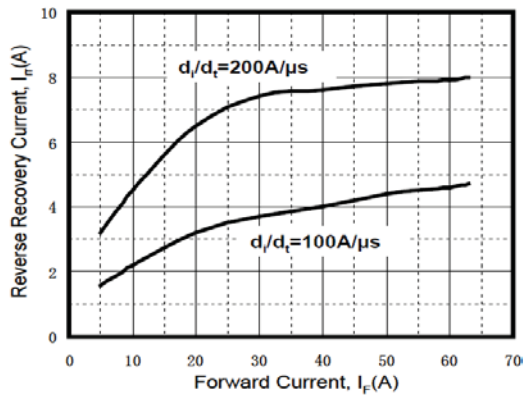


Figure 18. Reverse Recovery Current

Typical Characteristics

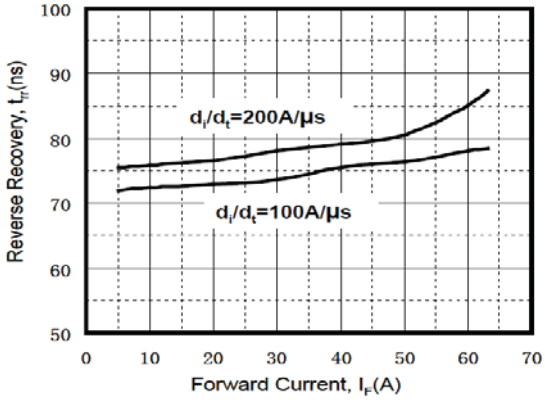


Figure 19. Stored Charge

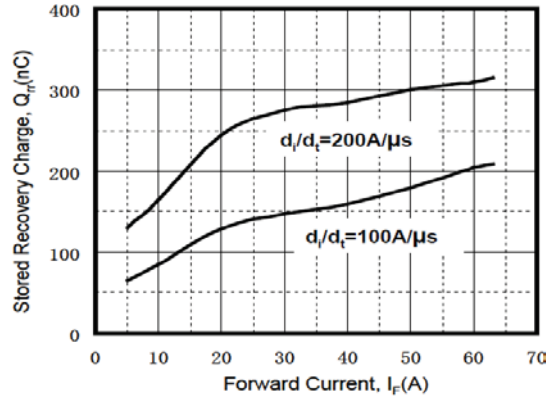


Figure 20. Reverse Recovery Time

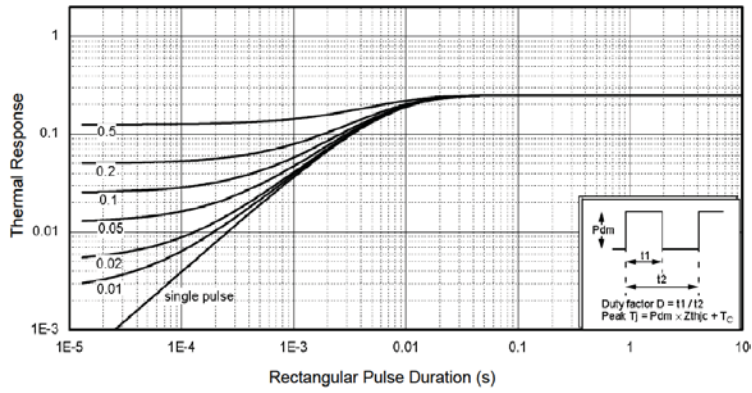


Figure 21. Transient Thermal Impedance of IGBT

Package Dimension

TO-264

